## **INSTITUTE OF NANO ELECTRONIC ENGINEERING**

## **LAB EQUIPMETS**

	IMAGE	EQUIPMENT/ITEM	DESCRIPTION
1		(Facilities) Chemical Room	Chemical Storage Facilities
2		(Facilities) Fume Hood	Scrubber system connected facilities.
3		(Facilities) DNA Booth	DNA Related activities
4	B	(Facilities) Electrical Properties Booth	Device characterization activities

5		(Facilities) Surface Analysis Booth	Morphology activities
6		(Analysis) Filmetrics F20-UV Thin Film Analyzer	<ul> <li>Non-reflective Thin film measurements</li> <li>Thickness Range 1nm~10μm</li> </ul>
7		(Analysis) (HPM) High Power Microscope 100X	<ul> <li>Photolithography Process Analysis</li> <li>Optical Observations at 10X~100X</li> </ul>
8		(Analysis) Dielectric Analyzer Novocontrol	Electrical Properties Characterization
9		(Analysis) 4-Point Probe/2-Point Probe/I-V Analyzer	Electrical Properties Characterization
10	Communication of the control of the	(Analysis) 3D Surface Profilometer	Surface Topography Analysis with 3D Imaging.

11	100 A DOCAR	(Equipment) Mask Aligner	Photolithography Process/Pattern Transfer
12		(Equipment) Spin Coater & Hot Plate	<ul> <li>Applying uniform thin films to a flat substrates such at coating photo resist on silicon wafer surface.</li> <li>To heat the (liquid &amp; solid) samples with adjustable heat and stir.</li> </ul>
13		(Facilities) Sample Storage	Lab sample and device storage facilities
14		(Facilities) Gas Room	Gas Support Facilities
15		(Equipment) LPCVD (Low Pressure Chemical Deposition)	Polysilicon Deposition Process
16		(Equipment) Wet & Dry Oxidation Furnace	<ul> <li>Grow Silicon Dioxide on the silicon surface</li> <li>Temperature up tp 1100°C</li> </ul>

17	(Equipment) Plasma Preen System	<ul> <li>Substrates Cleaning</li> <li>Using O2 as an ozone ambient.</li> </ul>
18	(Equipment) Thermal Evaporator PVD	Applying very thin layer by thermal evaporation for various PVD process
19	(Equipment) ICP-RIE Samco RIE-10iP	<ul> <li>Inductively Coupled Plasma-Reactive-ion etching Process</li> <li>Chemically reactive plasma to remove material deposited on wafers</li> </ul>
20	(Equipment) Muffle Furnace	Annealing Process with Temperature up to 1100°C.
21	(Equipment) RTA (Rapid Thermal Anneal) RTO (Rapid Thermal Oxide)	To anneal rapid sample at temperature 1100°C.
22	(Equipment) Thermo-Shaker Biosan TS-100	DNA Samples shaker

23	(Analysis) UV/VIS Spectrometer Lambda 35 PerkinElmer	Analyze solid/liquid/Powder thru optical characterization.
24	(Equipment) Autoclave	Sterilizer to most DNA/Bio related process components.
25	(Equipment) Centrifuge 5430-R	DNA and other molecules extraction Process
26	(Facilities) Laminar Flow Cabinet	Capable of UV curing
27	(Facilities) Material Preparations	
28	(Facilities) DI Water System (Deionized Water)	Stand-alone unit providing Deionized Water range 4~18 MΩ

29		(Equipment) Gravity/Natural Convection Oven	Hydro thermal growing of nano structure
30	- Control of the Cont	(Facilities) Ultra sonic Cleaning	Samples and apparatus cleaning facilities
31		(Equipment) Vacuum Oven	Heat treatment for > 98% RH
32		(Analysis) Photoluminescence (PL) Horiba	Contactless, nondestructive method to probe the electronic structure of materials
33		(Analysis) Scanning Electron Microscope (SEM-EDX) JEOL JSM-6010LV OXFORD Instrument	<ul> <li>Resolution Range 4 nm</li> <li>Magnification Range 5X to 300X.</li> </ul>
34		(Facilities) Scrubber System	Exhaust and neutralize the contaminants to the outside environment.

35	(Analysis) Potentiostat Metrohm Autolab PGSTAT204	Electrical properties and characterization for CV test
36	(Analysis) Spectrophotometer DS-11 Series	<ul> <li>Compact instrument delivers full spectrum UV-Vis analysis and fluorescence capability</li> </ul>